

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

Claims 1-18 (Canceled)

Claim 19 (Currently amended): A method of manufacturing a semiconductor device comprising:

forming a semiconductor film having a thickness between 150 and 1000 Å over a substrate;

emitting a pulse laser light [[beams]] at a rate of N pulses [[beams]] per second;

shaping the pulse laser light [[beams]] into a beam [[beams]] elongated in one direction at an irradiation surface through an optical system, the beam [[beams]] having a normal-distribution type energy profile of width L (m) perpendicular to the direction, where L is larger than zero, and the beam [[beams]] having substantially a constant energy distribution along the direction;

applying the beam [[beams]] to an arbitrarily selected portion of the semiconductor film; and

scanning the semiconductor film with the beam [[beams]] perpendicular to the direction at a speed V (m/s),

wherein the number of beams applied to the arbitrarily selected portion in one scan satisfies a relationship $3 \leq LN/V \leq 100$, and

wherein the width L (m) is defined as a beam [[beams]] in a region having 5% or more of an energy density with respect to a maximum energy density of the beam [[beams]] on the irradiation surface.

Claim 20 (Previously Presented): The method of claim 19 wherein the width is between 0.1 and 1 cm.

Claim 21 (Currently amended): The method of claim 19 wherein the beam [[beams]] along the direction has a length between 10 and 30 cm.

Claim 22 (Previously Presented): The method of claim 19 wherein the scanning step is conducted in air.

Claim 23 (Currently amended): A method of manufacturing a semiconductor device comprising:

forming a semiconductor film having a thickness between 150 and 1000 Å over a substrate;

emitting a pulse laser light [[beams]] at a rate of N pulses [[beams]] per second;

shaping the pulse laser light [[beams]] into a beam [[beams]] elongated in one direction at an irradiation surface through an optical system, the beam [[beams]] having a normal-distribution type energy profile of width L (m) perpendicular to the direction, where L is larger than zero, and the beam [[beams]] having substantially a constant energy distribution along the direction, and an average single-pulse energy density of the beam [[beams]] between 100 and 500 mJ/cm²;

applying the beam [[beams]] to an arbitrarily selected portion of the semiconductor film; and

scanning the semiconductor film with the beam [[beams]] perpendicular to the direction at a speed V (m/s),

wherein the number of beams applied to the arbitrarily selected portion in one scan satisfies a relationship $3 \leq LN/V \leq 100$, and

wherein the width L (m) is defined as a beam [[beams]] in a region having 5% or more of an energy density with respect to a maximum energy density of the beam [[beams]] on the irradiation surface.

Claim 24 (Previously Presented): The method of claim 23 wherein the width is between 0.1 and 1 cm.

Claim 25 (Currently amended): The method of claim 23 wherein the beam [[beams]] along the direction has a length between 10 and 30 cm.

Claim 26 (Previously Presented): The method of claim 23 wherein the scanning step is conducted in air.

Claim 27 (Currently amended): A method of manufacturing a semiconductor device comprising:

forming a semiconductor film having a thickness between 150 and 1000 Å over a substrate;

emitting a pulse laser light [[beams]] at a rate of N pulses [[beams]] per second;

shaping the pulse laser light [[beams]] into a beam [[beams]] elongated in one direction at an irradiation surface through an optical system, the beam [[beams]] having a normal-distribution type energy profile of width L (m) perpendicular to the direction, where L is larger than zero, and the beam [[beams]] having substantially a constant energy distribution along the direction;

applying the beam [[beams]] to an arbitrarily selected portion of the semiconductor film; and

scanning the semiconductor film with the beam [[beams]] perpendicular to the direction at a speed V (m/s),

wherein the pulse laser comprises an excimer laser,

wherein the number of beams applied to the arbitrarily selected portion in one scan satisfies a relationship $3 \leq LN/V \leq 100$ [[100]], and

wherein the width L (m) is defined as a beam [[beams]] in a region having 5% or more of an energy density with respect to a maximum energy density of the beam [[beams]] on the irradiation surface.

Claim 28 (Currently amended): The method of claim 27 wherein an average single-pulse energy density of the beam [[beams]] is between 100 and 500 mJ/cm².

Claim 29 (Previously Presented): The method of claim 27 wherein the width is between 0.1 and 1 cm.

Claim 30 (Currently amended): The method of claim 27 wherein the beam [[beams]] along the direction has a length between 10 and 30 cm.

Claim 31 (Previously Presented): The method of claim 27 wherein the scanning step is conducted in air.

Claim 32 (Currently amended): A method of manufacturing a semiconductor device comprising:

forming a semiconductor film having a thickness between 150 and 1000 Å over a substrate;

emitting a pulse laser light [[beams]] at a rate of N pulses [[beams]] per second;

shaping the pulse laser light [[beams]] into a beam [[beams]] elongated in one direction at an irradiation surface through an optical system, the beam [[beams]] having a trapezoidal energy profile of width L (m) perpendicular to the direction, where L is larger than zero, and the beam [[beams]] having substantially a constant energy distribution along the direction;

applying the beam [[beams]] to an arbitrarily selected portion of the semiconductor film;
and

scanning the semiconductor film with the beam [[beams]] perpendicular to the direction
at a speed V (m/s),

wherein the number of beams applied to the arbitrarily selected portion in one scan
satisfies a relationship $3 \leq LN/V \leq 100$, and

wherein the width L (m) is defined as a beam [[beams]] in a region having 5% or more of
an energy density with respect to a maximum energy density of the beam [[beams]] on the
irradiation surface.

Claim 33 (Previously Presented): The method of claim 32 wherein the width is between
0.1 and 1 cm.

Claim 34 (Currently amended): The method of claim 32 wherein the beam [[beams]]
along the direction has a length between 10 and 30 cm.

Claim 35 (Previously Presented): The method of claim 32 wherein the scanning step is
conducted in air.

Claim 36 (Currently amended): A method of manufacturing a semiconductor device
comprising:

forming a semiconductor film having a thickness between 150 and 1000 Å over a
substrate;

emitting a pulse laser light [[beams]] at a rate of N pulses [[times]] per second;

shaping the pulse laser light [[beams]] into a beam [[beams]] elongated in one direction
at an irradiation surface through an optical system, the beam [[beams]] having a trapezoidal
energy profile of width L (m) perpendicular to the direction, where L is larger than zero, and the

beam [[beams]] having substantially a constant energy distribution along the direction, and an average single-pulse energy density of the beam [[beams]] between 100 and 500 mJ/cm²;

applying the beam [[beams]] to an arbitrarily selected portion of the semiconductor film; and

scanning the semiconductor film with the beam [[beams]] perpendicular to the direction at a speed V (m/s),

wherein the number of beams applied to the arbitrarily selected portion in one scan satisfies a relationship $3 \leq LN/V \leq 100$, and

wherein the width L (m) is defined as beam [[beams]] in a region having 5% or more of an energy density with respect to a maximum energy density of the beam [[beams]] on the irradiation surface.

Claim 37 (Previously Presented): The method of claim 36 wherein the pulse laser comprises an excimer laser.

Claim 38 (Previously Presented): The method of claim 36 wherein the width is between 0.1 and 1 cm.

Claim 39 (Currently amended): The method of claim 36 wherein the beam [[beams]] along the direction has a length between 10 and 30 cm.

Claim 40 (Previously Presented): The method of claim 36 wherein the scanning step is conducted in air.

Claim 41 (Currently amended): A method of manufacturing a semiconductor device comprising:

forming a semiconductor film having a thickness between 150 and 1000 Å over a substrate;

emitting a pulse laser light [[beams]] at a rate of N pulses [[beams]] per second;

shaping the pulse laser light [[beams]] into a beam [[beams]] elongated in one direction at an irradiation surface through an optical system, the beam [[beams]] having a trapezoidal energy profile of width L (m) perpendicular to the direction, where L is larger than zero, and the beam [[beams]] having substantially a constant energy distribution along the direction;

applying the beam [[beams]] to an arbitrarily selected portion of the semiconductor film; and

scanning the semiconductor film with the beam [[beams]] perpendicular to the direction at a speed V (m/s),

wherein the pulse laser comprises an excimer laser,

wherein the number of beams applied to the arbitrarily selected portion in one scan satisfies a relationship $3 \leq LN/V \leq 100$, and

wherein the width L (m) is defined as a beam [[beams]] in a region having 5% or more of an energy density with respect to a maximum energy density of the beam [[beams]] on the irradiation surface.

Claim 42 (Previously Presented): The method of claim 41 wherein the width is between 0.1 and 1 cm.

Claim 43 (Currently amended): The method of claim 41 wherein the beam [[beams]] along the direction has a length between 10 and 30 cm.

Claim 44 (Previously Presented): The method of claim 41 wherein the scanning step is conducted in air.